

# 74ABT16244A

16-bit buffer/line driver; 3-state

Rev. 8 — 3 November 2011

Product data sheet

## 1. General description

The 74ABT16244A high-performance Bipolar CMOS (BiCMOS) device combines low static and dynamic power dissipation with high speed and high output drive.

The 74ABT16244A is a 16-bit buffer that is ideal for driving bus lines. The device features four output enable inputs ( $\overline{1OE}$ ,  $\overline{2OE}$ ,  $\overline{3OE}$ ,  $\overline{4OE}$ ), each controlling four of the 3-state outputs.

## 2. Features and benefits

- 16-bit bus interface
- Multiple  $V_{CC}$  and GND pins minimize switching noise
- Power-up 3-state
- 3-state buffers
- Output capability: +64 mA and -32 mA
- Live insertion and extraction permitted
- Latch-up performance: JESD 78 Class II
- ESD protection:
  - ◆ HBM JESD-A114E exceeds 2000 V
  - ◆ CDM JESD 22-C101-C exceeds 1000 V

## 3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74ABT16244ADGG	-40 °C to +85 °C	TSSOP48	plastic thin shrink small outline package; 48 leads; body width 6.1 mm	SOT362-1
74ABT16244ADL	-40 °C to +85 °C	SSOP48	plastic shrink small outline package; 48 leads; body width 7.5 mm	SOT370-1





## 5. Pinning information

### 5.1 Pinning

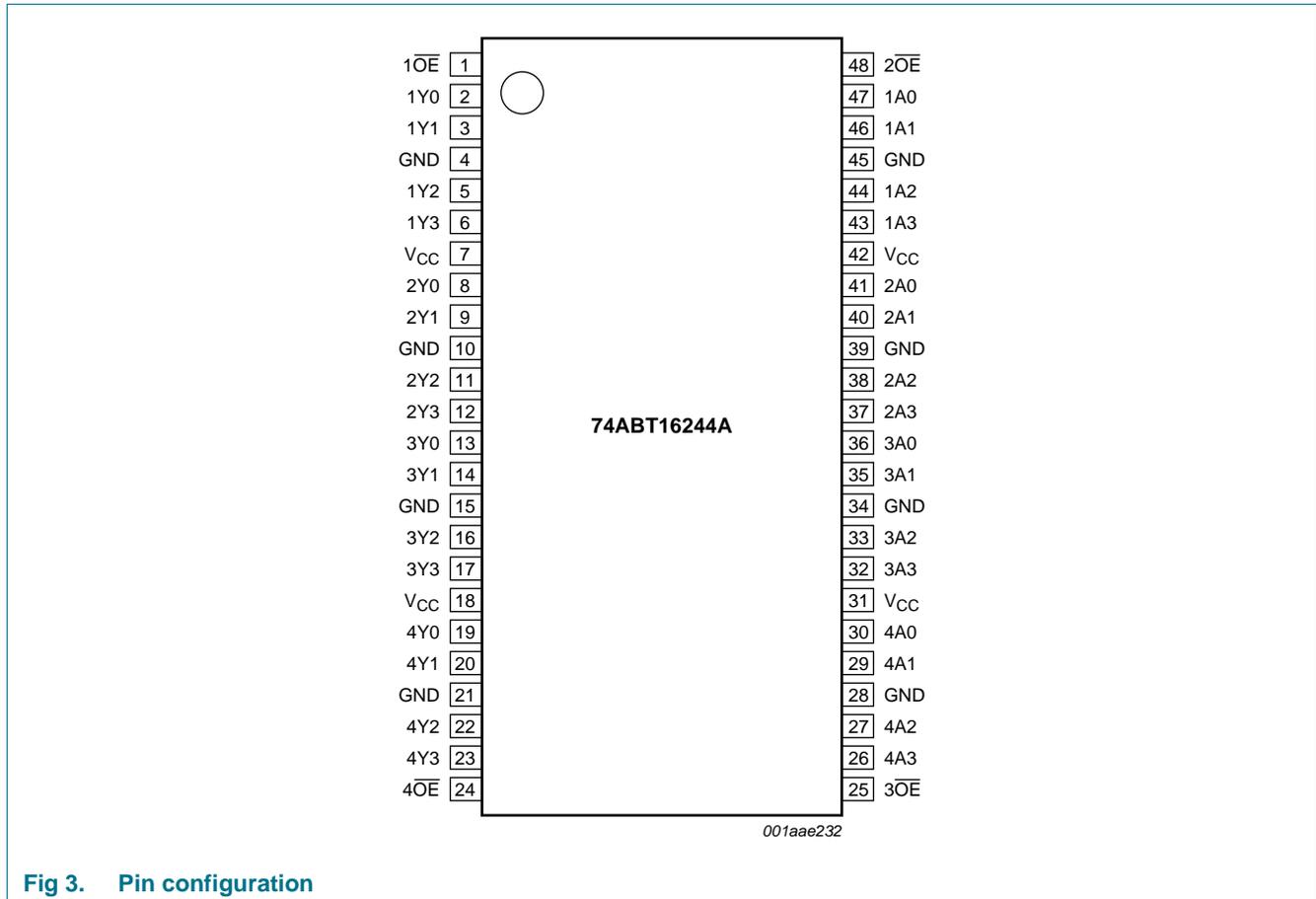


Fig 3. Pin configuration

### 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1OE	1	1 output enable (LOW active)
1Y[0:3]	2, 3, 5, 6	1 data output 0 to output 3
GND	4	ground (0 V)
V <sub>CC</sub>	7	supply voltage
2Y[0:3]	8, 9, 11, 12	2 data output 0 to output 3
GND	10	ground (0 V)
3Y[0:3]	13, 14, 16, 17	3 data output 0 to output 3
GND	15	ground (0 V)
V <sub>CC</sub>	18	supply voltage
4Y[0:3]	19, 20, 22, 23	4 data output 0 to output 3
GND	21	ground (0 V)

Table 2. Pin description ...continued

Symbol	Pin	Description
$\overline{4OE}$	24	4 output enable (LOW active)
$\overline{3OE}$	25	3 output enable (LOW active)
GND	28	ground (0 V)
4A[0:3]	30, 29, 27, 26	4 data input 0 to input 3
V <sub>CC</sub>	31	supply voltage
GND	34	ground (0 V)
3A[0:3]	36, 35, 33, 32	3 data input 0 to input 3
GND	39	ground (0 V)
2A[0:3]	41, 40, 38, 37	2 data input 0 to input 3
V <sub>CC</sub>	42	supply voltage
GND	45	ground (0 V)
1A[0:3]	47, 46, 44, 43	1 data input 0 to input 3
$\overline{2OE}$	48	2 output enable (LOW active)

## 6. Functional description

Table 3. Function table<sup>[1]</sup>

Control	Input	Output
nOE	nAn	nYn
L	L	L
	H	H
H	X	Z

- [1] H = HIGH voltage level;  
L = LOW voltage level;  
X = don't care;  
Z = high-impedance OFF-state.

## 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+7.0	V
V <sub>I</sub>	input voltage		<sup>[1]</sup> -1.2	+7.0	V
V <sub>O</sub>	output voltage	output in OFF-state or HIGH-state	<sup>[1]</sup> -0.5	+5.5	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < 0 V	-18	-	mA
I <sub>OK</sub>	output clamping current	V <sub>O</sub> < 0 V	-50	-	mA
I <sub>O</sub>	output current	output in LOW-state	-	128	mA
		output in HIGH-state	-	-64	mA
T <sub>j</sub>	junction temperature		<sup>[2]</sup> -	150	°C
T <sub>stg</sub>	storage temperature		-65	+150	°C

- [1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
[2] The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability.

## 8. Recommended operating conditions

Table 5. Operating conditions

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>CC</sub>	supply voltage		4.5	-	5.5	V
V <sub>I</sub>	input voltage		0	-	V <sub>CC</sub>	V
V <sub>IH</sub>	HIGH-level input voltage		2.0	-	-	V
V <sub>IL</sub>	LOW-level Input voltage		-	-	0.8	V
I <sub>OH</sub>	HIGH-level output current		-32	-	-	mA
I <sub>OL</sub>	LOW-level output current		-	-	64	mA
Δt/ΔV	input transition rise and fall rate		-	-	10	ns/V
T <sub>amb</sub>	ambient temperature	in free air	-40	-	+85	°C

## 9. Static characteristics

Table 6. Static characteristics

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		Unit	
			Min	Typ	Max	Min	Max		
$V_{IK}$	input clamping voltage	$V_{CC} = 4.5\text{ V}; I_{IK} = -18\text{ mA}$	-	-0.9	-1.2	-	-1.2	V	
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IL}$ or $V_{IH}$							
		$V_{CC} = 4.5\text{ V}; I_{OH} = -3\text{ mA}$	2.5	2.9	-	2.5	-	V	
		$V_{CC} = 5.0\text{ V}; I_{OH} = -3\text{ mA}$	3.0	3.4	-	3.0	-	V	
		$V_{CC} = 4.5\text{ V}; I_{OH} = -32\text{ mA}$	2.0	2.4	-	2.0	-	V	
$V_{OL}$	LOW-level output voltage	$V_{CC} = 4.5\text{ V}; I_{OL} = 64\text{ mA}; V_I = V_{IL}$ or $V_{IH}$	-	0.42	0.55	-	0.55	V	
$I_I$	input leakage current	$V_{CC} = 5.5\text{ V}; V_I = V_{CC}$ or GND	-	$\pm 0.01$	$\pm 1.0$	-	$\pm 1.0$	$\mu\text{A}$	
$I_{OFF}$	power-off leakage current	$V_{CC} = 0\text{ V}; V_I$ or $V_O \leq 4.5\text{ V}$	-	$\pm 5.0$	$\pm 100$	-	$\pm 100$	$\mu\text{A}$	
$I_{O(pu/pd)}$	power-up/power-down output current	$V_{CC} = 2.0\text{ V}; V_O = 0.5\text{ V}; V_I = \text{GND}$ or $V_{CC}; \overline{nOE} = \text{HIGH}$	[1]	$\pm 5.0$	$\pm 50$	-	$\pm 50$	$\mu\text{A}$	
$I_{OZ}$	OFF-state output current	$V_{CC} = 5.5\text{ V}; V_I = V_{IL}$ or $V_{IH}$							
		output HIGH-state at $V_O = 5.5\text{ V}$	-	0.1	10	-	10	$\mu\text{A}$	
		output LOW-state at $V_O = 0\text{ V}$	-	-0.1	-10	-	-10	$\mu\text{A}$	
$I_{LO}$	output leakage current	HIGH-state; $V_O = 5.5\text{ V}; V_{CC} = 5.5\text{ V}; V_I = \text{GND}$ or $V_{CC}$	-	5.0	50	-	50	$\mu\text{A}$	
$I_O$	output current	$V_{CC} = 5.5\text{ V}; V_O = 2.5\text{ V}$	[2]	-50	-100	-180	-50	-180	mA
$I_{CC}$	supply current	$V_{CC} = 5.5\text{ V}; V_I = \text{GND}$ or $V_{CC}$							
		outputs HIGH-state	-	0.45	1.0	-	1.0	mA	
		outputs LOW-state	-	10	19	-	19	mA	
		outputs 3-state	-	0.45	1.0	-	1.0	mA	
$\Delta I_{CC}$	additional supply current	per input pin; $V_{CC} = 5.5\text{ V};$ one input at 3.4 V and other inputs at $V_{CC}$ or GND	[3][4]	-	100	250	-	250	$\mu\text{A}$
$C_I$	input capacitance	$V_I = 0\text{ V}$ or $V_{CC}$	-	4	-	-	-	pF	
$C_{I/O}$	input/output capacitance	outputs disabled; $V_O = 0\text{ V}$ or $V_{CC}$	-	7	-	-	-	pF	

[1] This parameter is valid for any  $V_{CC}$  between 0 V and 2.1 V, with a transition time of up to 10 ms. From  $V_{CC} = 2.1\text{ V}$  to  $V_{CC} = 5\text{ V} \pm 10\%$ , a transition time of up to 100  $\mu\text{s}$  is permitted.

[2] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[3] This is the increase in supply current for each input at 3.4 V.

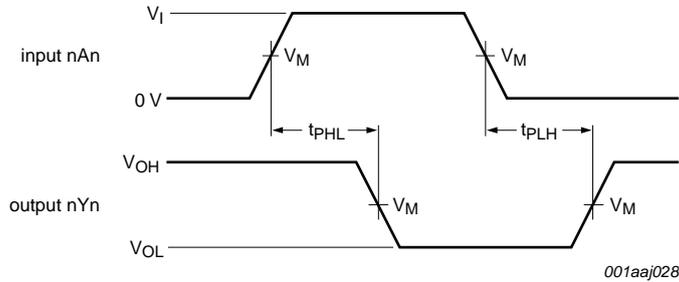
[4] This data sheet limit may vary among suppliers.

## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**  
*GND = 0 V. For test circuit, see [Figure 6](#).*

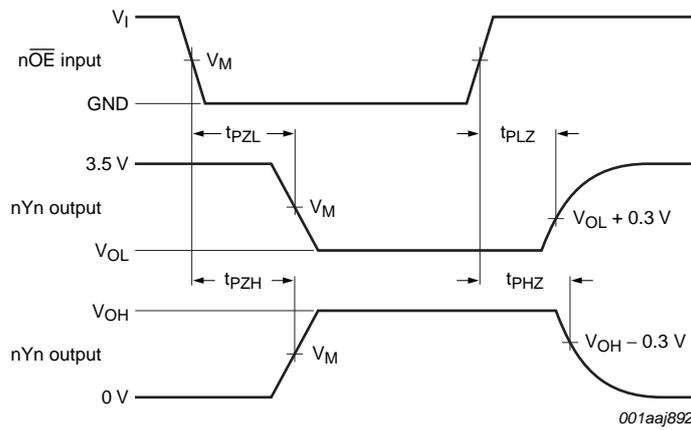
Symbol	Parameter	Conditions	25 °C; V <sub>CC</sub> = 5.0 V			–40 °C to +85 °C; V <sub>CC</sub> = 5.0 V ± 0.5 V		Unit
			Min	Typ	Max	Min	Max	
t <sub>PLH</sub>	LOW to HIGH propagation delay	nAn to nYn; see <a href="#">Figure 4</a>	1.1	1.7	2.6	1.1	2.8	ns
t <sub>PHL</sub>	HIGH to LOW propagation delay	nAn to nYn; see <a href="#">Figure 4</a>	1.3	2.1	2.9	1.3	3.4	ns
t <sub>PZH</sub>	OFF-state to HIGH propagation delay	n $\overline{\text{OE}}$ to nYn; see <a href="#">Figure 5</a>	1.6	2.7	3.7	1.6	4.5	ns
t <sub>PZL</sub>	OFF-state to LOW propagation delay	n $\overline{\text{OE}}$ to nYn; see <a href="#">Figure 5</a>	2.3	3.5	4.0	2.3	4.8	ns
t <sub>PHZ</sub>	HIGH to OFF-state propagation delay	n $\overline{\text{OE}}$ to nYn; see <a href="#">Figure 5</a>	1.5	3.0	4.0	1.5	4.6	ns
t <sub>PLZ</sub>	LOW to OFF-state propagation delay	n $\overline{\text{OE}}$ to nYn; see <a href="#">Figure 5</a>	1.6	2.4	3.2	1.6	4.1	ns

11. Waveforms



$V_M = 1.5\text{ V}$   
 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

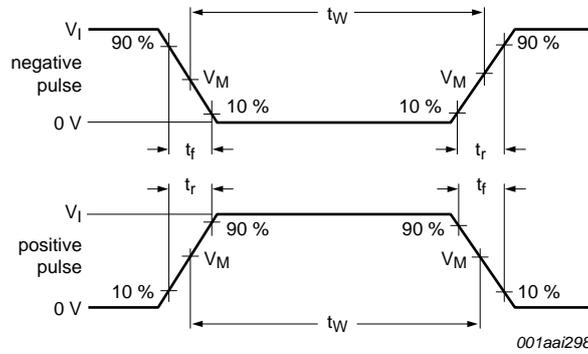
**Fig 4. Input (nAn) to output (nYn) propagation delay**



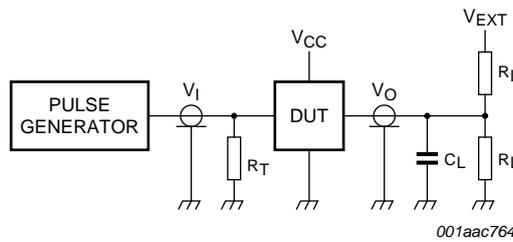
$V_M = 1.5\text{ V}$   
 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 5. 3-state output enable and disable times**

12. Test information



$V_M = 1.5\text{ V}$   
 a. Input pulse definition



Test data is given in [Table 8](#).

Definitions test circuit:

$R_L$  = Load resistance.

$C_L$  = Load capacitance including jig and probe capacitance.

$R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

b. Test circuit for 3-state outputs

Fig 6. Load circuitry for switching times

Table 8. Test data

Input				Load		$V_{EXT}$		
$V_I$	$f_i$	$t_w$	$t_r, t_f$	$C_L$	$R_L$	$t_{PHZ}, t_{PZH}$	$t_{PLZ}, t_{PZL}$	$t_{PLH}, t_{PHL}$
3.0 V	1 MHz	500 ns	2.5 ns	50 pF	500 $\Omega$	open	7.0 V	open

13. Package outline

TSSOP48: plastic thin shrink small outline package; 48 leads; body width 6.1 mm

SOT362-1

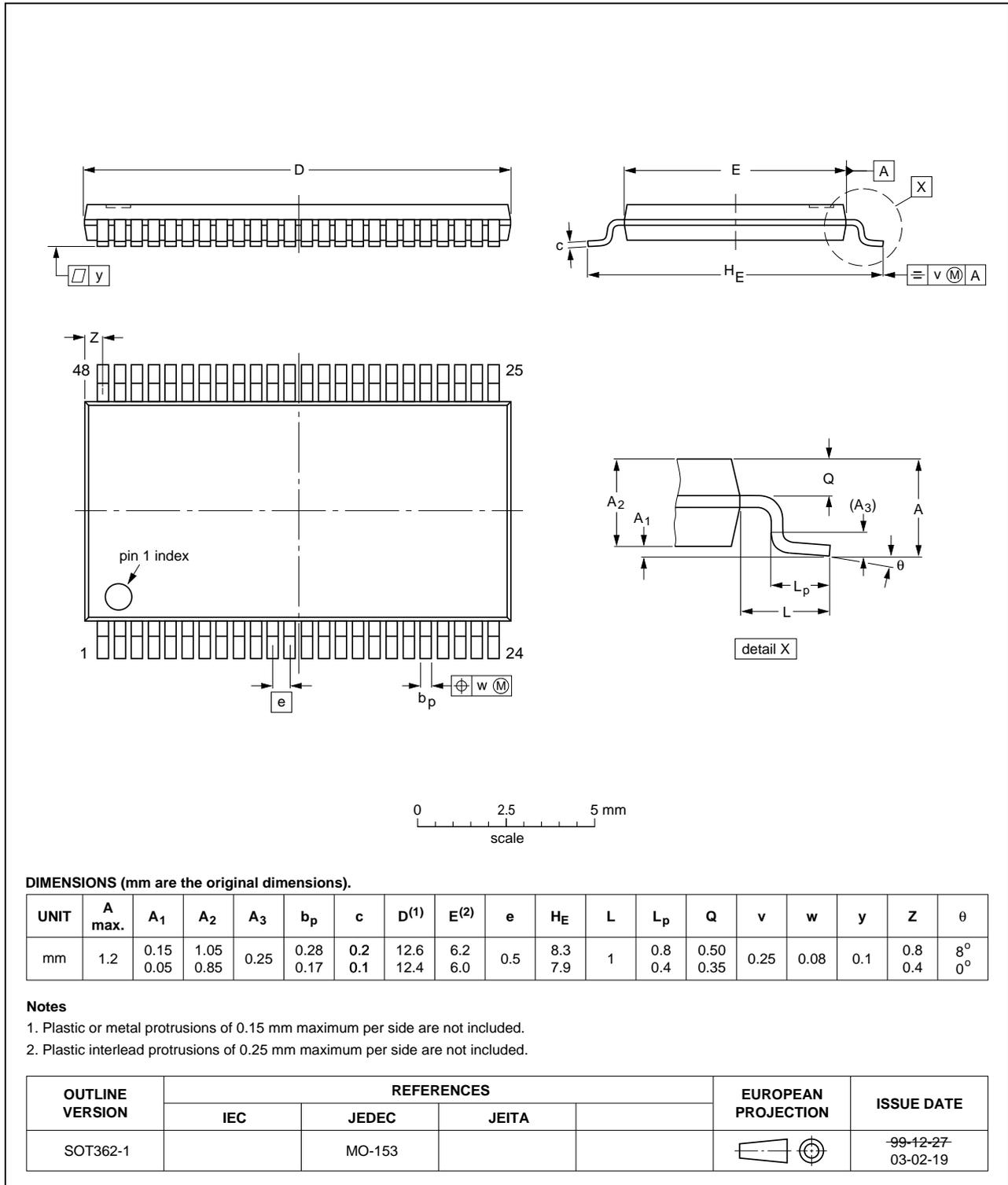


Fig 7. Package outline SOT362-1 (TSSOP48)

SSOP48: plastic shrink small outline package; 48 leads; body width 7.5 mm

SOT370-1

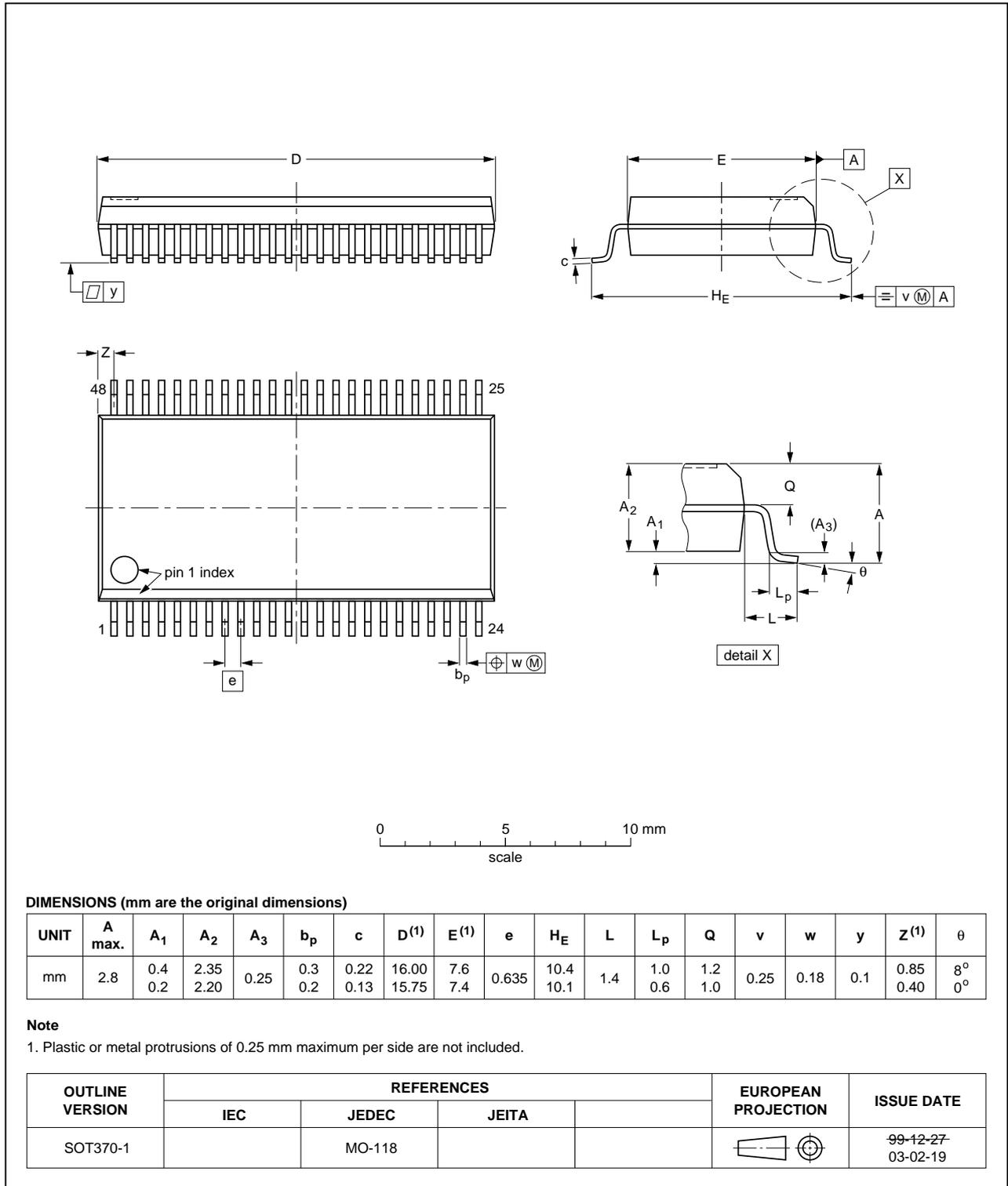


Fig 8. Package outline SOT370-1 (SSOP48)

## 14. Revision history

**Table 9. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
74ABT16244A v.8	20111103	Product data sheet	-	74ABT16244A v.7
Modifications:	• Legal pages updated			
74ABT16244A v.7	20100525	Product data sheet	-	74ABT16244A v.6
74ABT16244A v.6	20090323	Product data sheet	-	74ABT16244A v.5
74ABT16244A v.5	20060210	Product data sheet	-	74ABT_H16244A v.4
74ABT_H16244A v.4	19981007	Product specification	-	74ABT_H16244A v.3
74ABT_H16244A v.3	19980225	Product specification	-	74ABT_H16244A v.2

## 15. Legal information

### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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